

Reference No.: Dispatch No.: 070967 Dispatch Date: February 8, 2008

Notification of Reasons for Refusal

Patent Application No. 2004-015237

Drafting Date: February 6, 2008

Examiner: Sadayuki HASHIMOTO, 3747 3C00

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Applied Provision of the Patent Law: Section 29 (2)

The present application shall be refused for the following reasons. If the applicant intends to argue against this notification, it is necessary to file a written argument within 60 days from the dispatch date of this notification.

Reasons

The invention in accordance with the following claims could easily have been made by a person with ordinary skilled in the art to which the invention pertains, on the basis of an invention or inventions which were described in the following publication(s) distributed in Japan or elsewhere prior to the filing of the patent application or an invention or inventions made available to the public through electric telecommunication lines in Japan or elsewhere prior to the filing of the patent application. Accordingly, a patent shall not be granted under the Patent Law Section 29 (2).

Note (As to details of cited publications, refer to a list below.)

Claims 1-7

Cited Documents 1-5

Remarks:

The cited document 1 describes that polishing is performed with a polishing fluid, which is supplied between a polishing film and an object, while keeping a pH of the polishing fluid in a range of about 6, in which the polishing film is made of a substrate and a polishing layer that contains a binder resin and is formed on the substrate.

The invention of the above mentioned claims is achieved merely by incorporating the following known arts into the matter described in the cited document 1.

a. It is well known to keep the concentration of a polishing fluid during polishing (cf. the cited documents 2 and 3, for example).

b. It is well known to adjust a polishing fluid by adding ferric salts of ethylenediaminetetracetic acid (cf. the cited document 4, for example).

c. It is well known to contain various additives in a polishing film (cf. the cited documents 1 and 5, for example).

The list of the cited documents:

1. Japanese Patent Application Laid-open No. 2001-240849
2. Japanese Patent Application Laid-open No. 2000-326211
3. Japanese Patent Application Laid-open No. 2004-22804
4. Japanese Patent Application Laid-open No. 2003-211351
5. Japanese Patent Application Laid-open No. Hei-10-273648

<Matters to be Noted for the Amendments>

(Only the formal matters are stated in this section and therefore the English translation will be omitted for this section.)

Record on the Result of the Prior Art Search

• Fields to be Searched	IPC	B24B 1/00
		B24B19/00
		B24B21/00
		B24B55/02
		B24D 3/02
		B24D 3/28
		B24D11/00

- Prior Art Documents

1. Japanese Patent Application Laid-open No. 2003-260648
2. Japanese Patent Application Laid-open No. 2000-263449

This record of the result of the search for prior art documents will not constitute the reasons for refusal.

Should the applicant has any questions on the notification of reasons for refusal or request for interview, please contact the following person.

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